

Electronic Patent Application Fee Transmittal

Application Number:	10541154			
Filing Date:	30-Jun-2005			
Title of Invention:	Molding system having a micro heating element for molding a micro pattern structure			
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Filer:	Timothy E. Murphy/Jennifer Abernathy			
Attorney Docket Number:	1383-003			
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U.S. National Stage under 35 USC 371 Filing Fees				
Description	Fee Code	Quantity	Amount	Sub-Total in USD(\$)
Basic Filing:				
Pages:				
Claims:				
Miscellaneous-Filing:				
Petition:				
Patent-Appeals-and-Interference:				
Post-Allowance-and-Post-Issuance:				
Utility Appt Issue fee	2501	1	700	700
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Total in USD (\$)				1000